

Greeting from Chapter Chair:

Greetings to all EPS M'sia members for Y2018! How time flies, we are approaching the end of Y2018.

As updated in the 1H of the Y2018 newsletter, we are very glad that our prestigious and regionally recognized conference, International Electronics Manufacturing Technology (IEMT2018) conference, was held very successfully at the Historical City of Malacca back in September 2018. Volunteers from three sectors: local multinational semiconductor companies such as Infineon Technologies, Intel, ON Semiconductor, Carsem, Atotech, Lumileds, NXP, STMicroelectronics and Tactilis; local universities: UM, UKM, UTM and USM along with the semi-governmental body CREST, formed the organizing committee that would bring the conference to fruition. This year conference also achieved the highest number of participants in the history of IEMT with a total of 490 participants. Setting this as the new benchmark, I am expecting the IEMT2020 planned to be held in Kuala Lumpur to meet or exceed that.



Shaw Fong WONG
IEEE EPS M'sia
Chapter Chair 2018
Intel Technology

Moreover, the team had accomplished some other major milestones with their tireless volunteering to serve our technical community. Some of these landmark achievements are regional in nature, exemplified by our effort to table a meeting with 3 local Vietnamese Universities in March 2018 with the objective to help seed and initiate a Vietnam IEEE EPS chapter in Ho Chi Minh City. We had the backing of the Santa Clara EPS, Intel Vietnam and On Semiconductor Vietnam as it helps to raise regional technical expertise. We shared with them about global IEEE EPS society structure, our objectives and examples of benefits/activities of EPS Malaysia as an example. We are committed to support Vietnam team to achieve that goal, providing guidance and assistance into 2019.

On the local front, in Malaysia, we carried on organizing and funding the "Best Engineering Student Award" (BESA) program with certain identified local universities. This program aims to recognize and reward our final year engineering student's project with a prestigious award, thus encouraging the next generation engineers to pursue technical excellence. Another landmark achievement is the initiation and roll out of our long awaited membership reward program to all our long term engaged loyal members, which was executed. This aims to retain members whilst growing the society membership. We also extended our involvement to our regional EPS chapters by conducting some invited paper speaker sessions at China, Taiwan, Singapore and Hong Kong to exchange knowledge and ideas. In addition to all these, we revamped our chapter's website, aiming for better information dissemination, sharing, reference and also archiving. Please refer to [this link \(https://ieee-epsmalaysia.org\)](https://ieee-epsmalaysia.org) for more detail of our newly set up website! There are many more exciting programs that are being worked out by our committee and these are expected to produce results in 2019. Stay tune for that!

Lastly, I wish to take this opportunity to sincerely thank our chapter's ExCo members who always display a very great volunteering spirit for numerous years. I also want to wish you all a great Happy New Year 2019! We are in the right path to continue repositioning electronic packaging as a significant value creator and IP differentiator for various domains in this vibrant semiconductor industry, which includes 5G communication; autonomous driving and virtual reality devices. The heterogeneous packaging for big data, which presents many challenges in this fast paced world, also provides great opportunities for our respective industry groups to collaborate towards greater innovations. Looking forward to your participation and continued support in our exciting 2019 events!

IEEE EPS Vietnam Chapter Seeding and Initiation

(Compiled by CH Chew)

Looking back, Malaysia IEEE EPS chapter and IEMT conference would not have been successful without Dr. Bill Chen and our sister chapter, Santa Clara EPS chapter's great support 12 years back. Currently, with more investments into Vietnam (Intel, ON Semiconductor, Foxconn amongst others), there will be greater need to continue to bring up the knowledge and competency level of the local industries and universities associated with Semiconductor Packaging and Manufacturing Technology within Vietnam.

Inspired by Santa Clara EPS example of supporting the setup of a sister chapter in a new region, IEEE EPS Malaysia (SF Wong and CH Chew) initiated a face to face meeting with 3 local Vietnam Universities to discuss and advocate the setting up of a EPS chapter in Vietnam (VN). They had the support of Intel Vietnam and ON Semiconductor Vietnam, as well as Santa Clara EPS. SF and CH shared with the VN team about IEEE EPS objectives and examples of benefits/activities of EPS MY to enhancing knowledge and developing the country's human resources in the face of technical challenges. 2 sponsored tickets to IEMT2018 were presented to two of the Ho Chi Minh University heads of department to experience first hand the technical knowledge sharing available and what EPS VN could look like in years to come. The invited participants came and were impressed by how well EPS Malaysia organized the highly reputable IEMT conference successfully for numerous years.

Dr Bill Chen/Prof Sung Yi/Prof Kyung W. Paik/Dr Kim Shyong/Dr Cheong also thanked the University heads of department and Vietnam Engineers for taking the first step by attending EPS conferences. Furthermore, they motivated the delegates to continue participating in the regional EPS activities and strongly encouraged them to set up the sister chapter in Vietnam.

While there are many challenges to setting up the EPS chapter in Vietnam and improving the competencies of the local talents, the objective is achievable with the support of regional chapters. EPS Malaysia is committed to support Vietnam team to achieve that goal with the guidance and assistance from EPS headquarters.



Figure 1: SF Wong, CK Chew and the VN team



Figure 2: SF Wong, CK Chew and the VN team

EPS Engagement in CREST 2018 Semiconductor & Optoelectronics Bootcamp

EPS Malaysia chapter was invited to engage in the Collaborative Research in Engineering, Science & Technology (CREST) Semiconductor & Optoelectronics Cluster Bootcamp from 2nd to 5th of August 2018. In the evening of August 3rd, 5 young engineers from Intel Technology, representing IEEE/EPS chapter participated in the Young Engineers & Researchers @ Work dialogue session representing EPS Malaysia. Broken into smaller groups, bootcamp participants had the chance to personally get to know the young engineers.

The session started with the young engineers sharing on their journey from how they start their academic journey, to how they reach where they are today through good times and difficult times, to serve as a motivation and inspiration for the participants. 2-way interactions were highly emphasized during the session, with the participants interactively voicing out their concerns and questions to be discussed with the young engineers.

Despite the participants being exhausted, as it was the last program for the long day, the dialogue session was well received. The session was highly engaging, with participants still approaching the young engineers with more questions after the event ended. Many also come to personally thank the young engineers for their time and praising the sharing as motivational.



Figure 3: Participants engaged with the sharing (left), and group photo to end the fruitful session (right)

Summary of 38th IEMT Conference 2018, City of Melaka

(Compiled by Dr. Kim Shyong Siow, Ms. Vaithilingam Paramesvari, Mr. Jit-Shen Sim, photos by Mr. Chee Yang Ng)

It was poetically fitting that the IEMT Conference of 2018 was held in the Historic City of Melaka, having successfully made its presence felt in the other Historic City of Georgetown in 2016. Having hosted the event in 2010, Melaka embraced its Prodigal Conference's return with open arms, welcoming delegates from around the world once again in what has become the flagship conference of IEEE Santa Clara.

Volunteers from three sectors: local multinational semiconductor companies such as Infineon Technologies, Intel, ON Semiconductor, Carsem, Atotech, Lumileds, NXP, STMicroelectronics and Tactilis, local universities Universiti Kebangsaan Malaysia (UKM), Universiti Teknologi Malaysia (UTM) and Universiti Sains Malaysia (USM) along with the semi-governmental body CREST (Collaborative Research in Engineering, Science & Technology), formed the organizing committee that would bring the conference to fruition. 15 months of hard-work, enabled by multi-party conferencing, sprinkled with a gamut of emotions ranging from anticipation to angst and disappointment to delight, overtly fueled by the desire to bring the best conference to the society (covertly driven by the fear of failure), culminated in the 3-day Conference held from 4th to 6th September 2018 at the Ramada Plaza Hotel in the heart of Melaka city.



Figure 4: The IEMT 2018 Organizing Committee

The conference kicked off with a bang on the 4th of September with 7 short-courses covering the diverse topics of

- **Failure Analysis of Engineering Materials for Application in IoT** (Prof. Dr. Kuan Yew Cheong – USM),

- **Electromigration- The hurdle for Miniaturization of High Power Devices** (Dr. Ning-Cheng Lee – Indium)
- **PDC – Packaging for MEMS and Sensors** (Dr. Theuss Horst – Infineon)
- **Cu Wire Bonding for Automotive Grade Semiconductor Products Packaging** (Mr. Mark Luke Farrugia – NXP)
- **Chip to Package Interactions: Trends, Developments and Integration Challenges** (Dr. Srinivasa Yeduru – Infineon)
- **Wire Bond Advancement: Smart Equipment for Smart Manufacturing** (Mr. Nelson Wong – Kulicke & Soffa)
- **Breakthrough in Semiconductor Packaging Problem Solving Through Quality Function and Statistical Methodologies** (Mr. LF Chan – LF Training)

The short-course topics were well-received, garnering 138 participants who were impressed by the depth of knowledge as well as the breadth of coverage of the short-courses.



Figure 5: Dr. YY Tan (Left) and Mr. SF Wong (2nd from Right) with the Short-Course Speakers

The second day of the conference saw a Grand Ballroom packed with participants hungering for knowledge and information to be shared by the impressive line-up of speakers. After the welcome speeches by the IEMT2018 General Chair, Dr. Yik-Yee Tan and the IEEE EPS Malaysia Chapter Chair, Mr. Shaw Fong Wong, the evergreen Dr. Bill Chen took to the stage with an engaging speech that brought us back through memory lane, way back to before 2017, when the EPS – Electronics Packaging Society was still known by the tongue-

numbering acronym of CPMT – Components, Packaging and Manufacturing Technologies.



Figure 6: Packed Grand Ballroom for the Opening on 2nd Day

Emceeds Dr. Yew Hoong Wong, Bernard Lim and Jit-Shen Sim moderated the events in the main ballroom. The conference had the good fortune of witnessing 7 keynote speeches, each presented by renowned experts in their respective areas. The first two keynote addresses were delivered by Mr. Qin Deng (IBM) *The AI Driven Manufacturing Transformation is Imminent* and Ms. Claire Troadec (Yole Developpement) *Automotive Industry Transformation: EV/HEV impact on Power Modules, Design Changes and Packaging innovations!* Both keynote addresses showed key trends, challenges and opportunities for the semiconductor industry, keeping the audience engaged throughout the presentations. In the afternoon session, the 3rd Keynote address by Dr. Bill Chen (ASE) *Heterogeneous Integration through SiP from Design to Manufacturing* kept the audience equally engaged and this was no mean feat, considering that the keynote was given at 3pm, when bellies were full from the sumptuous lunch provided by the host hotel. The next three keynote addresses were presented in quick succession on the 3rd morning of the conference: Dr. NorAzmi Alias (CREST) *Opportunities and Challenges for Semiconductor and Optoelectronic Packages in the Emerging Markets of 4th Industrial Revolution (4IR)* focused on Digital Healthcare trends, Dr. Gaurang Choksi (Intel) *Enabling Heterogeneous Packaging: A Perspective on Challenges & Opportunities* focused on the multiple challenges in Heterogeneous Integration and Dr. Qian Wang (Tsinghua University) *Growth of China’s Semiconductor Advanced Packaging – A Win-Win in a World-Wide Context* opened our eyes towards the packaging industry in China. Rounding off the keynote addresses, the final keynote was presented in the evening by Mr.

Alexander Mueller (Infineon) *Packaging for Automotive: Challenges and Solutions*, giving us a glimpse of the challenges facing the automotive packaging world.



Figure 7: Keynote Speaker Dr. Bill Chen

Adding more spice to the program, a panel discussion was introduced in this Conference, right after lunch on the second day. Moderated by Mr. Jit-Shen Sim (Infineon), the panelists Ms. Claire Troadec (Yole Developpement), Mr. Laurent Herard (STMicroelectronics) and Mr. Alexander Mueller (Infineon) shared their perspectives on the megatrends of New Mobility Services, Electrification, Digitization and Autonomous Driving in the automotive industry. Packaging paradigm shifts, challenges and related strategies were also put on the table for discussions. Overall, the one-hour was well spent in a balance of technical facts, opinions and sharing of knowledge even from the audience. On top of the already excellent program line-up, kudos to the Program team of Swee Har, Eng Hoo and Bernard for this additional gem.

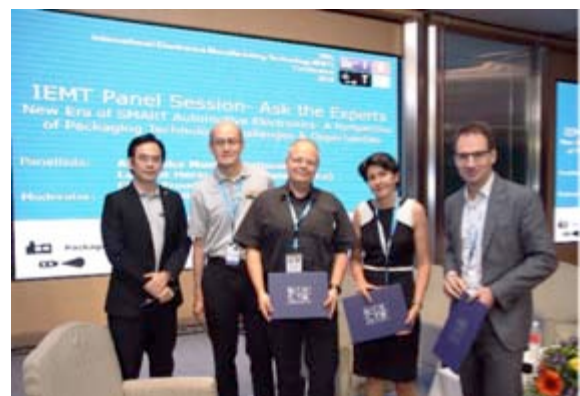


Figure 8: Panel Discussion on the Automotive Industry (Moderator Jit-Shen Sim, Conference Advisor Chee Hiong Chew, Mr. Alexander Mueller, Ms. Claire Troadec, Mr. Laurent Herard)

For those hankering for some statistics about the conference, here are some numbers to sate your appetite:

- 490 total participants
- 138 Short-Course attendees
- 62 Oral Papers
- 22 table exhibits
- 17 invited Papers
- 17 poster papers
- 17 International Advisory Board (IAB) members
- 7 Short courses
- 7 Keynote addresses

The conference accomplished several record-breaking feats, accumulating the highest sponsorship with 22 display booths – congratulations to the Sponsor & Exhibition team of Chan Wah Chai, Lily Khor and Eng-Lim. The former achievement surely brought a smile of relief to the treasurers, Shutesh and Kai Chat. IEMT2018 also achieved the highest number of participants at 490. This feat would not have been possible without the tireless efforts by the Publicity and Publication team of Chee Yang, Kim Shyong and Yew Hoong, aided of course by the International Advisory Board consisting of 17 members from across the globe. Coupled with the timely selection of the 7 short-course workshops, this was also a job well done by the International Liaison team of Poh Leng, Mun Leong and Jit-Shen. The Technical team of Prof. Nasir, Prof. Cheong, Choong Kooi, Hoo Kooi and Zal should also be lauded for wading through >100 abstract submissions to arrive at a final 62 oral paper and 17 poster paper presentations. These were presented à la quad-core during the conference: in four separate break-out rooms while the posters were presented along the main walkway, visible to all conference participants.

Throughout the conference, the secretariat team, led by Param, did a fantastic job of maintaining order, accommodating changes and last-minute registrations. They did such a good job that we barely noticed them because no news is good news. Kudos to Madam Secretary Param and her team!!!

But what is a conference in a much-touted historic city if there was no chance to soak in the sights, sounds and smell of the host city? With this rhetorical question in mind, the Logistics and

Social Tour team of Nor Azman, Kenneth and MdNasir Mislán treated conference participants to a pre-Gala Dinner excursion through the city of Melaka in an idyllic boat-ride, coasting along the Sungai Melaka, river breeze gently caressing faces and billowing hair as we welcomed dusk in this historic city. After disembarking from the boats, participants had the opportunity to hitch a ride in colorful trishaws as the sun set further, casting an ethereal glow as we made our way back to the hotel for the Gala Dinner.



Figure 9: Cruise on the Melaka River and Beca (Trishaw) Ride

The Gala Dinner got off to an explosive start with delectable dances that showcased the variety of races in Malaysia. Mr. Chee Hong Lee, President and Managing Director of Infineon Malaysia, set the ball rolling with his Opening Address, cementing his commitment to the conference (Infineon had sent about 100 participants to the conference). The scrumptious servings of local cuisine, the cheerful conversations among table mates and the melodious music from the live band all conspired to create the perfect ambience for a gala dinner, and not even a technical talk during the banquet could ruin the atmosphere. In fact, Dr. Ricky Lee's SMART Talk was so inspiring it got a rapturous round of applause from the still sober audience. Of course it helped that Dr. Lee concluded his talk with the assertion that "the louder you clap, the smarter you are". Throughout the dinner, the lovely emcee, Poh Leng, kept the audience informed and inspired.



Figure 10: Mr. Chee Hong Lee (President and Managing Director of Infineon Melaka)

Engineers are nurtured to take pride in sharing knowledge but it is human nature to compete among ourselves. No conference would be complete without some friendly competition. Judged by Prof. Nasir, Prof. Cheong, Dr. Poh-Leng Eu, Dr. Shutesh Krishnan and Mr. Hoo Kooi Lim (now you know who to thank/blame), the Best Poster was awarded to Dr. Lai Chun Yung (Infineon) for his paper entitled *Investigation of the Solder Void Formation Mechanism After High Temperature Stress Process by 3D CT Scan and EDX Analysis*. The Best Student Paper went to Yan-Cheng Liu, Hsien-Chie Cheng and Zong-Da Wu of Feng Chia University, Taiwan with the paper entitled *Evaluation of Out-of-plane Deformation of Fan-out Wafer-level Packaging* while the Best Industry Paper was awarded to Yung Hsiang Lee, Wei Keat Loh and Ian Chin of Intel with *Electronic Packaging Moisture Interaction Study*.

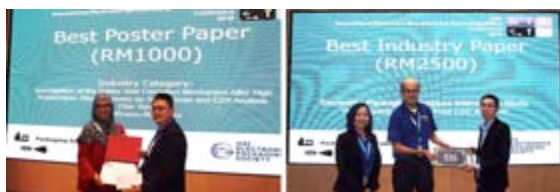


Figure 11: Winners for Poster and Industrial Paper

All good things have an end (except the sausage which has two) and so it was that the Conference ended after all lucky draw prizes were distributed. Not even the World Cup witnessed so many heartaches in this final session as many of lucky draw winners turned up unlucky, having left the conference early (you know who you are) thus disqualifying themselves from the prizes. After all the laughter and claps, it was time to bring down the curtains on IEMT2018, dubbed the best conference in Melaka, JB and some say Batam. Alas, the bitter-sweet moment of friends and acquaintances having to part ways after a successful conference came to pass but then again, there is always the next conference in two years' time. See you in Putrajaya, Malaysia in 2020!



Figure 12: Participants at Posters displayed



Figure 13: Group and individual photos at IEMT 2018

Scientific Writing & Publishing Session – University of Nottingham Malaysia

(Compiled by Dr. Kim Shyong Siow)

The Institute of Mechanical Engineers Student Chapter of University of Nottingham Malaysia Campus and IEEE Electronic Packaging Society (EPS) Malaysia jointly organized a session to educate students on technical publication of their research work on the 6th of Dec 2018 where Dr. Kim S Siow (UKM) spoke on “Scientific Writing and Publishing” in a two-hour talk. More than 30 students attended the 2-hour session, mostly from the fourth year Mechanical Engineering embarking on their upcoming research projects. Dr. Kim Shyong Siow touched on various elements of scientific publications - the motivation for publishing, aspects of a manuscript (i.e. abstracts, introduction, experimental procedures, results and discussions, and conclusions), different forms of publications, ethics and authorship. Dr Kim Siow also made his recent Kindle book on the same topic available for free of charge for the participants. The participants left the talk feeling motivated and equipped with the right skills and attitude to writing their next manuscript for publication. Kudos to Dr. Siow for encouraging more publications!



Figure 14: Dr. KS Siow sharing the methodology



Figure 15: Dr. Siow sharing a photo moment with a student

IEEE Day & UniMAP Student Branch Adoption Program – Industrial Lecture

(Compiled by Dr. Shutesh, Dr. Banu and Encik Hafiz)

UniMAP organized an Industrial Lecture program in conjunction with the IEEE Day 2018 at their Pauh Campus, Perlis. A total of 96 participants consisting of staff, postgraduate and undergraduate students from the School of Microelectronic Engineering attended this event.

The organizer had a mini exhibition for students to get to know IEEE and its activities. Pamphlets and brochures with information related to IEEE societies and membership benefits were available at the exhibition. IEEE Day 2018 Ambassador for Malaysia Section, (Mohd Hafiz Ismail) delivered the opening speech and briefed on the history and information of IEEE, IEEE Malaysia Section and IEEE UniMAP Student Branch. At the end of the event Dr Shutesh from EPS Malaysia delivered a lecture titled “Towards Nano-dimensional Electronic Packaging”.



Figure 16: Dr. Shutesh delivering his lecture.



Figure 17: Group photo at UniMAP for IEEE Day

Industrial Open Day – University of Malaya

(Write-up by Dr. Yew Hoong Wong)

On 28th November 2018, Industrial Open Day was held in Block Y, Department of Electrical Engineering, Faculty of Engineering, University of Malaya. Industrial Open Day was organized by Malaya Electrical Students Association (MESA) in collaboration with the following societies - **IEEE Electronics Packaging Society (EPS)**, IEEE Electron Devices Society, IEEE Computational Intelligence Society and IEEE Dielectrics and Electrical Insulation Society. Over 200 students, lecturers and representatives from 14 companies participated in the event. Out of the 14 companies, 10 were invited to each conduct an industrial talk for the event. The companies were KVC, Li-Zainal, ABB Malaysia, Micron Malaysia, Telekom Malaysia, SilTerra, PESTECH Technology, Infineon, Western Digital and Huawei.

The event first started with an opening ceremony in Auditorium 2, Block Y. At 2pm, the Head of Department of Electrical Engineering, Associate Professor Dr Suhana Binti Mohd Said kickstarted the event by delivering an opening speech. Then at 2.05pm, the Deputy Dean of Postgraduate Studies, Professor Ir. Dr. Hazlie Bin Mokhlis was invited on stage to deliver his welcoming speech. The event continued with a mock cheque giving ceremony. Prof. Hazlie were asked to remain on stage. The representative from KVC, Ms. Samantha Ooi followed by the representative from Li-Zainal, Ir. Lee Tze Lin were invited on stage to pass the mock cheques to Prof. Hazlie subsequently. KVC was named the Platinum Sponsor of the event whereas Li-Zainal was named the Long-term Partner of MESA. A group photo was taken afterwards.

At 2.30pm, a forum titled “Entrepreneur Success Story – Inspiring Journey of Tech Startup” moderated by Associate Professor Dr. Narendra Kumar was conducted. The four panellists – Mr Joe McGuire, the Founder and CEO of MyMy Payments Malaysia, Ms Sharmila Sharma, the Head of Strategy and Mergers & Acquisitions with Cenergi SEA, Mr Thomas Yip, the Founder and CEO of Radica Software, and Mr Noor Mohd Helmi Bin Nong Hadzmi, the Founder and CEO of IX Telecom were invited on stage to share their stories of entrepreneurship. The sharing followed by a Q&A session took about 30 minutes. Students then moved to the lobby of Block Y to visit booths from some of the industrial companies set up there.

The next agenda of the event was the three sessions of parallel industrial talks conducted in DK7, DK8, DK9 and Huawei Lab in Block Y. The first session started at 3.30pm and ended at 4.00pm. Huawei, ABB, Micron and TM each conducted an industrial talk in Huawei Lab, DK7, DK8 and DK9 respectively. Students were allowed to join any talks that they were interested in. The next session started at 4.10pm and ended at 4.40pm. SilTerra, PESTECH Technology and KVC each conducted an industrial talk in DK7, DK8 and DK9 respectively. The last session of parallel industrial talks started at 4.50pm and ended at 5.20pm. Infineon, Li-Zainal and Western Digital each conducted an industrial talk in DK7, DK8 and DK9 respectively. Students and representatives from the company were asked to fill in feedback forms after each talk.

The last agenda of the event, which started at 5.30pm, was the interview session for internship or job placement. Prior to the event, resumes from students were collected online and sent to the companies participating in the event. Only Huawei and PESTECH Technology conducted the interview sessions. The representatives from Huawei interviewed the students in Meeting Room 1, Student Clinic and Huawei Lab whereas PESTECH Technology conducted the interview in Meeting Room 2 of Block Y. The event officially ended at 7.30pm.

A lucky draw was conducted the next day. Students who attended the Industrial Open Day were each given an attendance card. Stickers were given to stick on the card as proofs of visiting the booths and attending the industrial talks. To qualify for the lucky draw, a student must visit three booths and attend three industrial talks. Prizes included were four Starbucks gift cards worth RM50, 10 SanDisk Ultra Dual Drive 16 GB sponsored by Western Digital and a wireless mouse. Winners were announced live on MESA’s official Facebook.



Figure 18: Group photo of the participants



Figure 19: Entrepreneur Success Story session panelists



Figure 20: Industry Booth display



Figure 21: Registration and Information Desk



Figure 22: Students in one of the parallel session talks



Figure 23: Inspiring students to change the world

EPS BESA and Electronic Packaging Track Awards 2018

(Compiled by Dr. Kim Shyong Siow)

Best Engineering Student Awards (BESA) for 2018 Undergraduate Winners

EPS Malaysia has a regular “Best Engineering Student Awards (BESA)” for Undergraduates. This is the 2nd year of its roll out and the aim is to reward and encourage technical excellence in Malaysia’s next generation of engineers. Congratulations to the winners who receive cash prize of RM 3,000 and a certificate from IEEE EPS!

Student	Supervisor	Final Year Paper Title	University
Tong Teong Yen	Dr. Yap Soon Poh	Investigation on Plane Failure Mechanisms of Structural Bamboo under Different Loadings	University of Malaya
Jacqueline Lease	Assoc Prof Dr Ahmad Azmin Mohamad	Electrochemical Characterization of Lithium Vanadium Oxide Anode with Agar Binder in Aqueous Rechargeable Lithium Ion Batteries	University of Sains Malaysia
Mohd Soufian Kamarudin	Dr. Muhammad Noor Afiq Witri Muhammad Yazid	Alumina Thermal Paste for Enhancing Cooling Performance of CPU	Universiti Teknologi Malaysia
Lai Chun Neng	Dr T. Nandha Kumar	FPGA-based Accelerometer	University of Nottingham (Malaysia Campus)



Figure 23: Jacqueline Lease receiving certificate from Prof Dr. Ir. Cheong Kuan Yew



Figure 24: Tong Teong Yen receiving the certificate from Ir. Dr. Wong Yew Hoong



Figure 25: Mohd Soufian receiving the certificate from Assoc. Prof. Dr. Haslinda Mohamed Kamar



Figure 26: Lai Chun Neng receiving his EPS certificate from Dr. Siow at his graduation ceremony

IEEE Malaysia Section’s Best FYP Award 2018 - Track 6: Electronics Packaging

The awards for this track, were sponsored by, Electronics Packaging Society (EPS) for the Final Year Paper (FYP). Congratulations to the winners! The winners won cash prizes of RM 300, RM 200 and RM 100 respectively for Best FYP, 1st runner up, and 2nd runner up.

Award	Student	Supervisor	FYP Title	University
Best FYP	Thines a/l Ravendran	Dr. Imaduddin Helmi Bin Wan Nordin	Effect of Laser Pulse Energy on Temperature Distribution on Laser Irradiation of Monocrystalline Silicon	Universiti Malaysia Perlis
1 st runner up	Lai Keng May	Dr. Yeo Kwok Shien	SECS/GEM Protocol Integration and Data Processing for Real-Time SMT Equipment Monitoring	Tunku Abdul Rahman Universiti College
2 nd runner up	Shri Kumaran a/l Nadaraja	Dr. Yap Boon Kar	Lead Frame Tape Assessment	Universiti Tenaga Nasional



Figure 27: Electronics Packaging Track Group Photo



Figure 28: The Award winners, their supervisors and the judges

REGIONAL EVENTS:

20th International Conference on Electronic Materials and Packaging (EMAP)

(Compiled by Dr. Yew Hoong Wong)

Dr. Wong YH represented Malaysia EPS chapter to join the 20th International Conference on Electronic Materials and Packaging (EMAP 2018) on the 17 – 20 Dec 2018. This conference was held in Hong Kong, a gateway in between the East and West. The purpose of the conference is to promote awareness of new advances in materials, design and simulations, fabrication, reliability, and thermal management of microsystem/MEMS packages. This conference uses Hong Kong University of Science and Technology (HKUST) as the meeting venue. With a rich, successful history of previous EMAP conferences held in Japan, Korea, Malaysia, Singapore, and Taiwan, this annual event offers a great opportunity to unite people from academia, research institutions and industries to share their innovative thoughts, state-of-the-art technologies and recent developments. The program included invited and keynote presentations from world-renowned speakers, interactive sharing sessions, and technical short courses. An excursion was also arranged after the technical sessions to showcase the natural part of Hong Kong. This conference had 2 short courses, 8 keynote speakers, 14 invited paper, 60 oral presentation papers and multiple poster papers, which attracted more than 150 participants from around the globe.



Figure 29: Dr. Wong with Dr. Jeffrey CC Lo



Figure 30: EMAP Steering Committee at lunch

20th Electronics Packaging Technology Conference (EPTC) and IEEE Electronic Packaging Society Board of Governors Meeting (BoGM)

(Compiled by Dr. Shutesh Krishnan)

EPS society held its BoGM meeting in Singapore this year. This is the first time BoGM is held outside the United States. Dr Shutesh represented EPS Malaysia in this meeting. The conference was held from 4-7th Dec at Resort World, Sentosa following EPTC 2018, Singapore. Delegates from EPS chapters around the world attended this meeting. The meeting was scheduled for two days. On the first day, 7th Dec, the meeting was stated with a reception dinner for the delegates. This provided opportunity for the delegates to meet and greet their counterparts from various countries. Dr Shutesh presented EPS Malaysia's accomplishments to the delegates later in the evening. He also promoted the upcoming IEMT 2020 event in Malaysia.

On the second day of the meeting, 8th Dec, the society President Avram Bar Cohen, presented his report on EPS's accomplishments for the year. This is followed by report presentation from Technology, Education and Conference functional teams. The nomination chair presented the names of the new members at large. The Vice president of publication presented the recommendation on open access for EPS journal/transactions. The EPS President elect was also nominated during the meeting. Chapter chairs from regions 8, 10 and Young professionals also presented their respective activities for the year. The meeting was ended with decision to convene again for the next BoGM in 2019 following 69th ECTC in Las Vegas, NV, USA

19th International Conference on Electronic Packaging Technology (ICEPT)

(Compiled by Shaw Fong Wong)

SF Wong represented Malaysia EPS in the ICEPT 2018 and was invited to present a keynote “Why Packaging Still Matters” there. It was a good opportunity to explore possibilities for potential collaboration and also for benchmarking. ICEPT had about 450 delegates from >20 countries with > 350 papers covering 7 parallel sessions and multiple poster sessions. The conference was hosted by IMCES and organized by Fudan University (Shanghai) at the beautiful Crowne Plaza Hotel of Shanghai Harbour City. Both IEEE EPS and EMPT are the technical sponsors for this regional conference. The event was opened by EPS President, Prof. Avram Bar-Cohen and some keynotes were delivered by Distinguish Speakers like Prof Rao Tumalla, Prof CP Wong, Dr. Rolf Aschenbrenner and Prof David Wei Zhang. The Malaysian team received very warm hospitality from the Fudan University and also the China Electronic Packaging team and they in turn extended an invitation to the China team to attend IEMT 2018 in Malaysia as distinguished speakers. Good engagement with China EPS & packaging team to initiate greater future collaborations between China and Malaysia teams. EPS MY wishes to thank Prof Cai from Beijing Tsing Hua University for their kind invitation for Malaysia EPS to participate in this!!



Figure 31: A great get together sessions with respective organizers (Fudan University & EPS China) as well as the international delegates

2018 International Microsystems, Packaging, Assembly & Circuits Technology (IMPACT)

(Compiled by Dr. Yik Yee Tan)

This year, International Microsystems, Packaging, Assembly and Circuits Technology (IMPACT) conference was organized by EPS, iMAPS Taiwan, ITRI and TPCA in the beautiful city Taipei, Taiwan. The theme was “IMPACT on Artificial Intelligence – Our Future”. It attracted more than 600 delegates with > 200 papers covering 4 parallel sessions and multiple poster sessions. On another floor, there was a Taiwan Printed Circuit Association (TPCA) show focusing on Assembly, Green Technology, Printed Circuit Board (PCB) and Thermal exhibition. There were around 250 exhibitors who came with new machines or products demo, mainly from Taiwan and China. Dr. Tan YY represented Malaysia EPS chapter and presented a technical paper entitled “investigation on Cu-Al Intermetallic Compound”. Malaysia EPS received very warm hospitality from the organizing committee and had great opportunities to interact with local industrial and academia for technical sharing, potential collaboration and benchmarking. Malaysia EPS team also extended our Invitation to the IMPACT participants and other renowned speakers to participate in the IEMT2020 conference, where they were invited to deliver keynotes as Distinguish speakers. This showed a good continuity and good engagement with Taiwan EPS & packaging team to spark more future collaborations.



Figure 32: Dr. Yik Yee Tan at IMPACT 2018

Up Coming EPS Conferences & Meetings:

Networking and constant knowledge advancement opportunities are always an important part of any conference. EPS chapters have lined up an outstanding program with top tier speakers and timely topics for 2018. Below is a sample of what's in store for us. Mark the dates!!

EPS CONFERENCES IN 2019:

<https://ieee-epsmalaysia.org/events-activities/upcoming-events/>

Some Important References:

- Official IEEE website: <http://www.ieee.org>
- Official IEEE/EPS website (HQ) <https://eps.ieee.org/>
- IEEE EPS Malaysia website: <https://ieee-epsmalaysia.org/>